

Taiwan Semiconductor

N-Channel Power MOSFET

60V, 38A, 17mΩ

FEATURES

- 100% avalanche tested
- Suitable for 5V drive applications
- Pb-free plating
- RoHS Compliant
- Halogen-Free according to IEC 61249-2-21

KEY PERFORMANCE PARAMETERS				
PARAMETER		VALUE	UNIT	
V _{DS}		60	V	
R _{DS(on)} (max)	$V_{GS} = 10V$	17	mΩ	
	V _{GS} =4.5V	20		
Q_g		15	nC	

APPLICATION

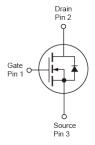
- SMPS Synchronous Rectification
- Networking DC-DC Power System











ABSOLUTE MAXIMUM RATINGS (T _A = 25°C unless otherwise noted)					
PARAMETER		SYMBOL	LIMIT	UNIT	
Drain-Source Voltage		V_{DS}	60	V	
Gate-Source Voltage		V_{GS}	±20	V	
Continuous Drain Current (Note 1)	T _C = 25°C	I _D	38	А	
	T _C = 100°C		24		
Pulsed Drain Current (Note 2)		I _{DM}	152	Α	
Single Pulsed Avalanche Energy (Note 3)		E _{AS}	20	mJ	
Single Pulsed Avalanche Current (Note 3)		I _{AS}	20	Α	
Total Power Dissipation @ T _C = 25°C		P _{DTOT}	46	W	
Operating Junction and Storage Temperature Range		T _J , T _{STG}	- 55 to +150	°C	

THERMAL PERFORMANCE				
PARAMETER	SYMBOL	LIMIT	UNIT	
Junction to Case Thermal Resistance	$R_{\Theta JC}$	2.7	°C/W	
Junction to Ambient Thermal Resistance	$R_{\Theta JA}$	62	°C/W	

Notes: $R_{\theta JA}$ is the sum of the junction-to-case and case-to-ambient thermal resistances. The case thermal reference is defined at the solder mounting surface of the drain pins. $R_{\theta JA}$ is guaranteed by design while $R_{\theta CA}$ is determined by the user's board design. $R_{\theta JA}$ shown below for single device operation on FR-4 PCB in still air

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ELECTRICAL SPECIFICATIONS (T _A = 25°C unless otherwise noted)						
PARAMETER	CONDITIONS	SYMBOL	MIN	TYP	MAX	UNIT
Static (Note 4)						
Drain-Source Breakdown Voltage	$V_{GS} = 0V, I_D = 250\mu A$	BV _{DSS}	60			V
Gate Threshold Voltage	$V_{DS} = V_{GS}, I_{D} = 250uA$	$V_{GS(TH)}$	1.2	1.7	2.5	V
Gate Body Leakage	$V_{GS} = \pm 20V, V_{DS} = 0V$	I _{GSS}			±100	nA
Zero Gate Voltage Drain Current	$V_{DS} = 60V, V_{GS} = 0V$	I _{DSS}			1	μΑ
	$V_{DS} = 48V, V_{GS} = 0V,$ $T_{J} = 125^{\circ}C$				10	
	V _{GS} = 10V, I _D = 20A	R _{DS(ON)}		15	17	mΩ
Drain-Source On-State Resistance	V _{GS} = 4.5V, I _D = 10A			17.5	20	
Dynamic (Note 5)						
Total Gate Charge		Q_g		15		
Gate-Source Charge	$V_{DS} = 30V, I_{D} = 10A,$	Q_{gs}		5.5		nC
Gate-Drain Charge	$V_{GS} = 4.5V$	Q_{gd}		5		
Input Capacitance		C _{iss}		900		
Output Capacitance	$V_{DS} = 25V, V_{GS} = 0V,$ f = 1.0MHz	C _{oss}		130		pF
Reverse Transfer Capacitance	7 I = 1.0IVIDZ	C _{rss}		90		
Gate Resistance	F = 1MHz, open drain	R_g		2.2		Ω
Switching (Note 6)	· · · · · · · · · · · · · · · · · · ·					
Turn-On Delay Time	$V_{GS} = 10V, V_{DS} = 15V,$ $R_{G} = 6\Omega, I_{D} = 1A$	t _{d(on)}		8.6		
Turn-On Rise Time		t _r		24.2		
Turn-Off Delay Time		t _{d(off)}		32.3		ns
Turn-Off Fall Time		t _f		7.9		
Source-Drain Diode (Note 4)						
Diode Forward Voltage	V _{GS} =0V, I _S =10A	V _{SD}			1	V
Reverse Recovery Time	V _{GS} = 0V, I _S = 10A	t _{rr}		18		ns
Reverse Recovery Charge	dI _F /dt = 100A/μs	Q _{rr}		10		nC

Notes:

- 1. Current limited by package
- 2. Pulse width limited by the maximum junction temperature
- 3. L = 0.1 mH, $I_{AS} = 20 \text{A}$, $V_{DD} = 50 \text{V}$, $R_G = 25 \Omega$, Starting $T_J = 25 ^{\circ}\text{C}$
- 4. Pulse test: PW ≤ 300µs, duty cycle ≤ 2%
- 5. For DESIGN AID ONLY, not subject to production testing.
- 6. Switching time is essentially independent of operating temperature.

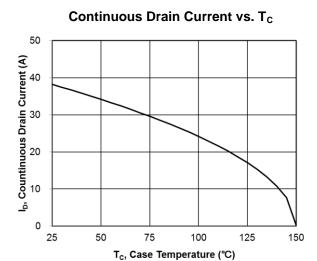
ORDERING INFORMATION

PART NO.	PACKAGE	PACKING
TSM170N06CH C5G	TO-251(IPAK)	75pcs / Tube
TSM170N06CH X0G	TO-251S(IPAK SL)	75pcs / Tube



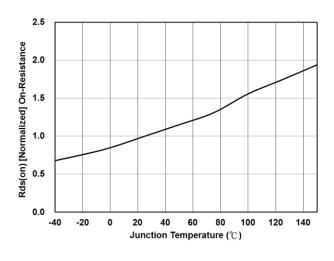
CHARACTERISTICS CURVES

(T_C = 25°C unless otherwise noted)

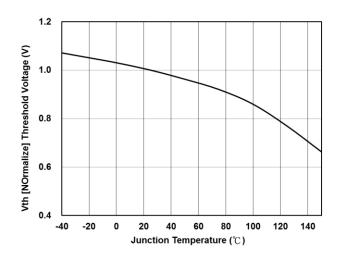


Gate Charge 10 V_{DS}=30V ID=10A 10 V_{DS}=30V ID=10A 10 Q_g, Total Gate Charge (nC)

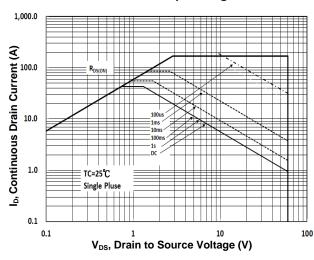
On-Resistance vs. Junction Temperature



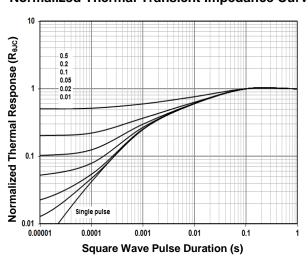
Threshold Voltage vs. Junction Temperature



Maximum Safe Operating Area



Normalized Thermal Transient Impedance Curve



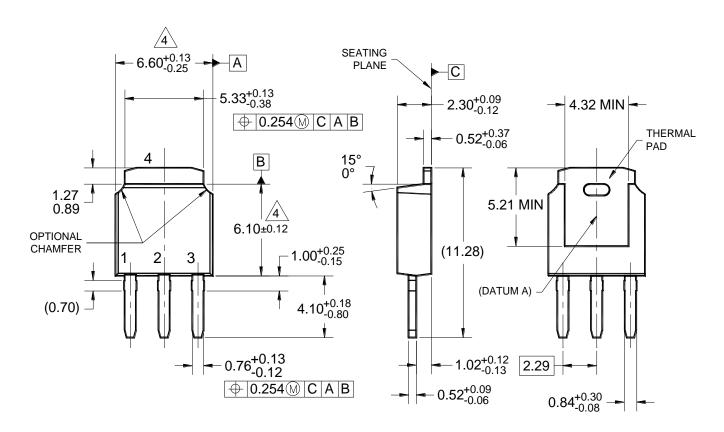
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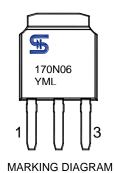
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PACKAGE OUTLINE DIMENSIONS (Unit: Millimeters)

TO-251S (IPAK SL)





P/N = MARKING CODE

Y = YEAR CODE

M = MONTH CODE FOR HALOGEN FREE PRODUCT

O=JAN P=FEB Q=MAR R=APR S=MAY T=JUN U=JUL V=AUG W=SEP X=OCT Y=NOV Z=DEC

L = LOT CODE

NOTES: UNLESS OTHERWISE SPECIFIED

- 1. ALL DIMENSIONS ARE IN MILLIMETERS.
- 2. DIMENSIONING AND TOLERANCING PER ASME Y14.5M-1994.
- 3. EXCEPT LEAD LENGTH, THE JEDEC REFERENCE IS TO-251, VARIATION AA.

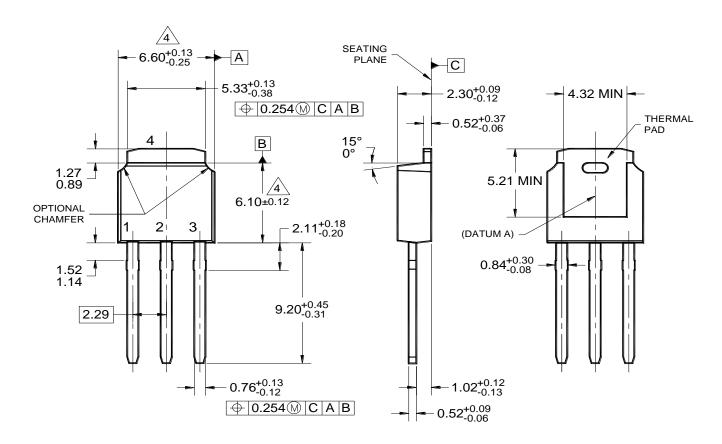
MOLDED PLASTIC BODY DIMENSIONS DO NOT INCLUDE MOLD FLASH, PROTRUSIONS OR GATE BURRS.

5. DWG NO REF: HQ2SD07-IPAKSL-006 REV A.

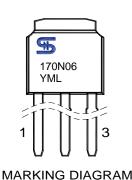


PACKAGE OUTLINE DIMENSIONS (Unit: Millimeters)

TO-251 (IPAK)



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Y = YEAR CODE

M = MONTH CODE FOR HALOGEN FREE PRODUCT

L = LOT CODE

NOTES: UNLESS OTHERWISE SPECIFIED

- 1. ALL DIMENSIONS ARE IN MILLIMETERS.
- 2. DIMENSIONING AND TOLERANCING PER ASME Y14.5M-1994.
- 3. THIS CONFORM TO JEDEC PACKAGE REGISTRATION TO-251, VARIATION AA.
- MOLDED PLASTIC BODY DIMENSIONS DO NOT INCLUDE MOLD FLASH, PROTRUSIONS OR GATE BURRS.

5. DWG NO REF: HQ2SD07-IPAK-005 REV A.



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